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(12) **United States Design Patent**  
**Celaya et al.**

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(54) **SEMICONDUCTOR DEVICE PACKAGE**  
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(\*\*) Term: **14 Years**

(21) Appl. No.: **29/211,047**

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(51) **LOC (8) Cl.** ..... **13-03**

(52) **U.S. Cl.** ..... **D13/182**

(58) **Field of Search** ..... D13/182; 174/52.1,  
174/52.2, 52.4, 666, 669, 675, 676, 678,  
690, 692, 696, 697, 730, 787; 361/773,  
820; 438/64, 65

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(57) **CLAIM**

We claim the ornamental design for a semiconductor device package, as shown and described.

**DESCRIPTION**

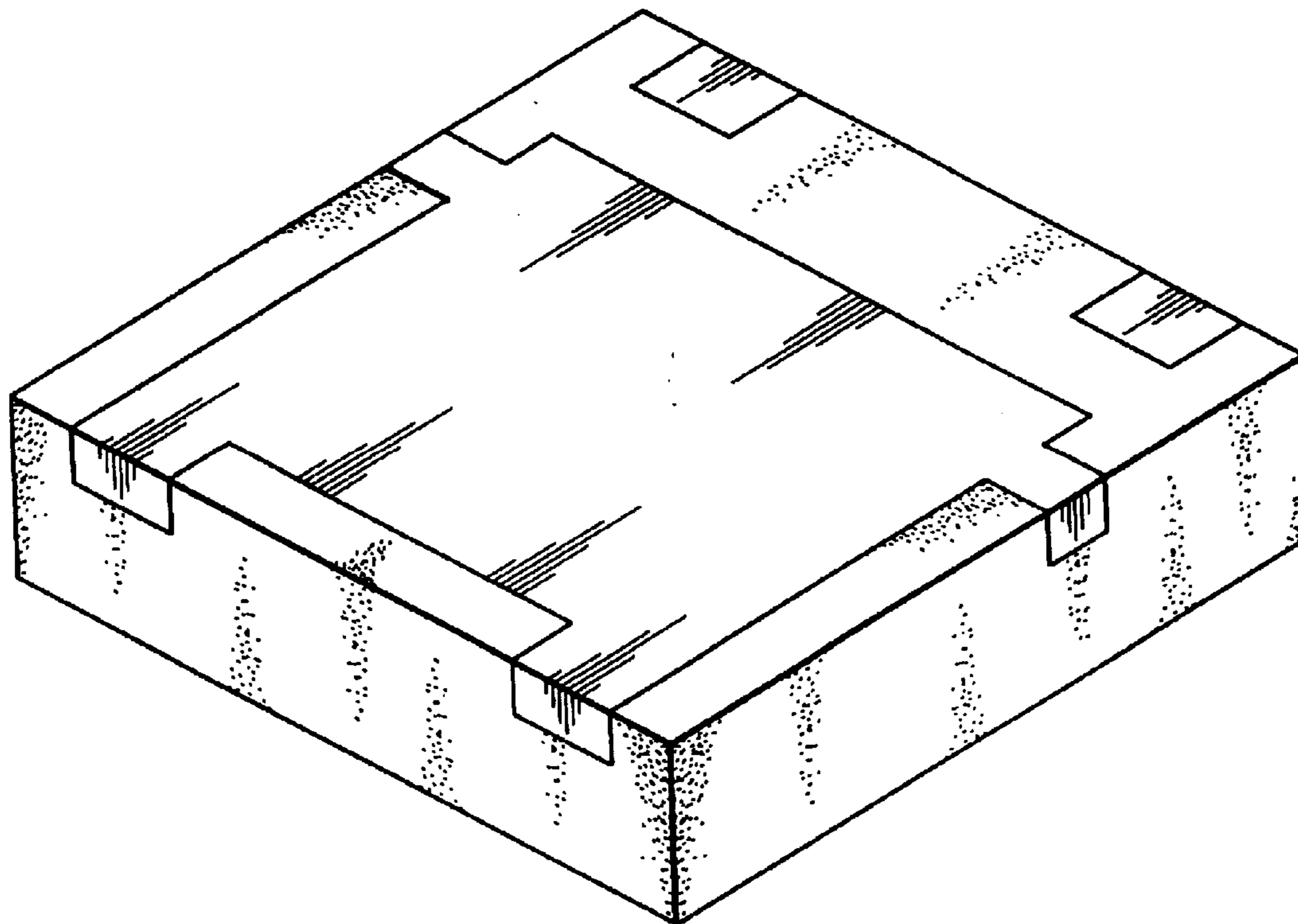
FIG. 1 is a perspective view from the front left side and below the semiconductor device package showing our new design.

FIG. 2 is a top plan view thereof;

FIG. 3 is a bottom plan view thereof; and,

FIG. 4 is an elevational view from the front side thereof.

**1 Claim, 3 Drawing Sheets**



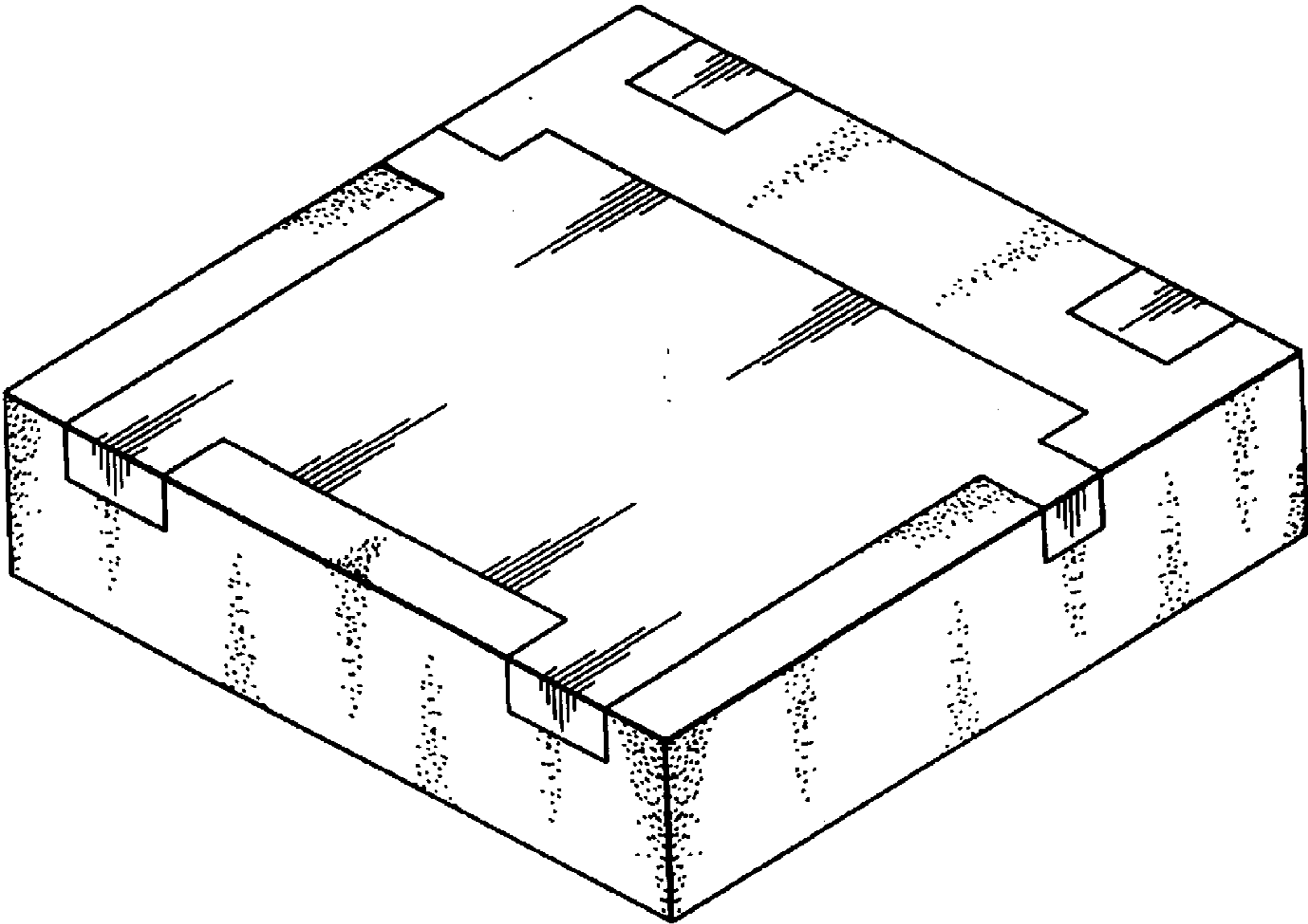


FIG. 1

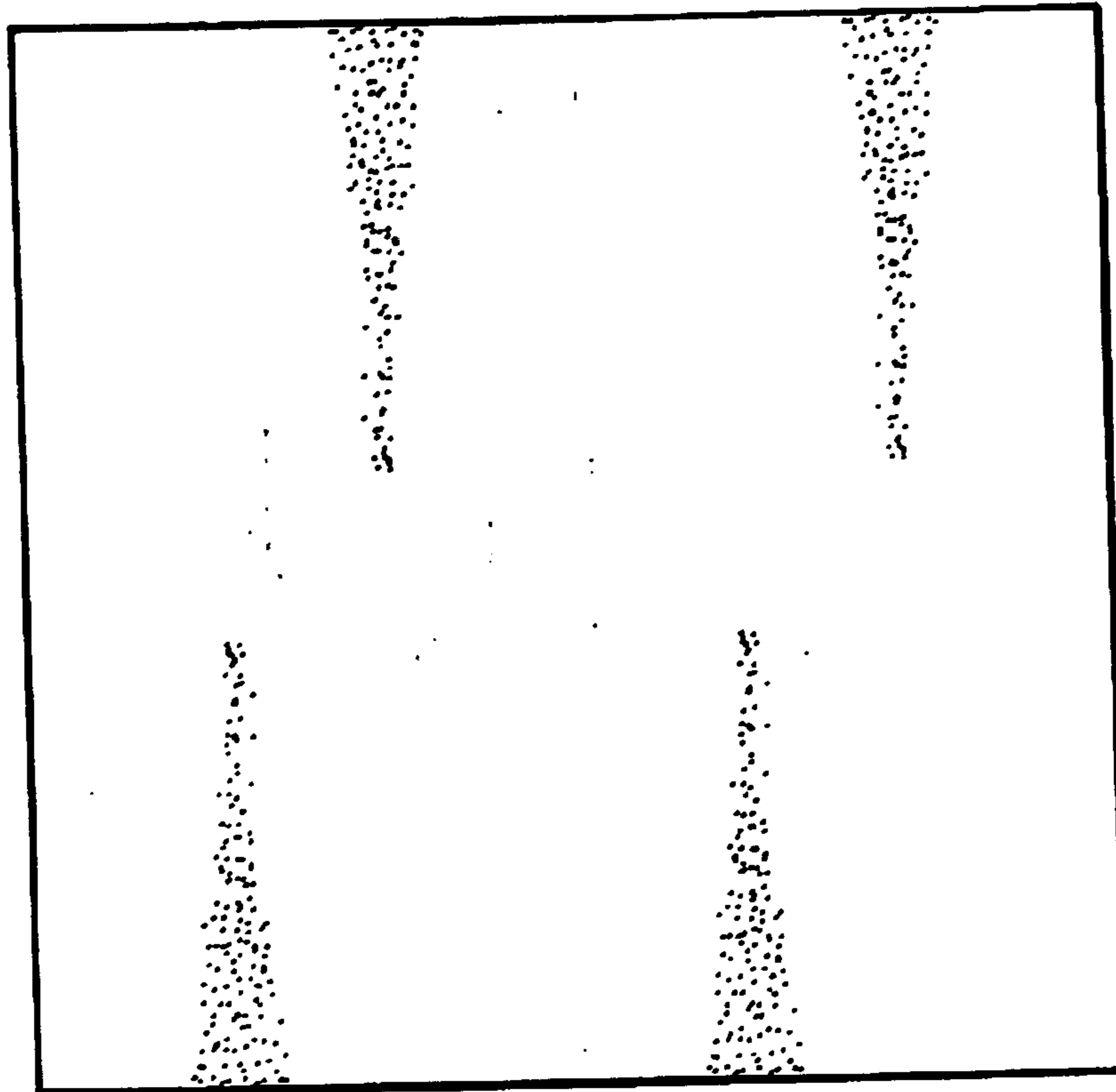


FIG. 2

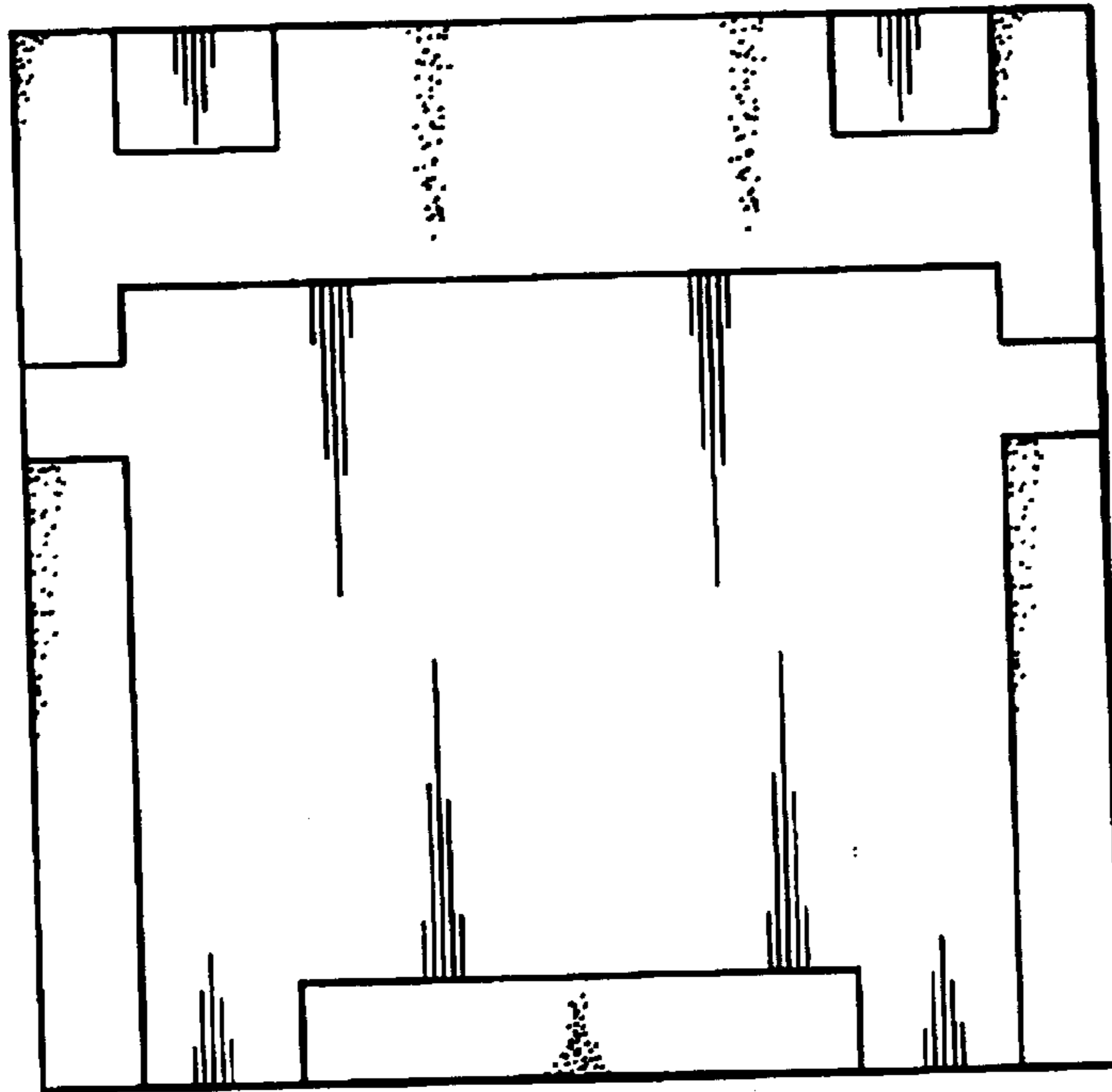


FIG. 3

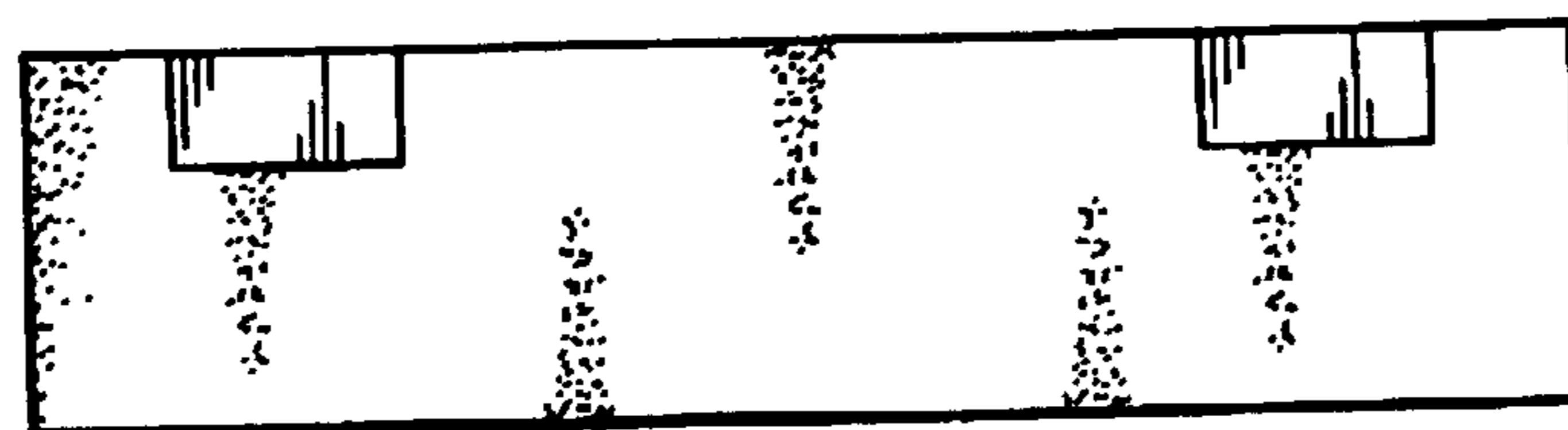


FIG. 4